


CASE NO.	485B
STATUS	ON SEMICONDUCTOR STANDARD
NEW STD	
USED ON	20 PIN MLF 0.5mm PITCH



ON Semiconductor 	MECHANICAL OUTLINES DICTIONARY	98AON01111D	
		PAGE	485B
DO NOT SCALE THIS DWG	ALL APPROVAL SIGNATURES ON FILE IN DOCUMENT CENTRAL	ISSUE 0	SHEET 2 OF 3

NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETERS
3. DIE THICKNESS ALLOWABLE IS 0.305MM MAXIMUM(.012 INCHES MAXIMUM).
4. DIMENSION D APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.20 AND 0.25MM FROM TERMINAL.
5. THE PIN #1 IDENTIFIER MUST BE EXISTED ON THE TOP SURFACE OF THE PACKAGE BY USING INDENTATION MARK OR OTHER FEATURE OF PACKAGE BODY.
6. EXACT SHAPE AND SIZE OF THIS FEATURE IS OPTIONAL.
7. THE SHAPE SHOWN ON FOUR CORNERS ARE NOT ACTUAL I/O.
8. PACKAGE WARPAGE MAX 0.05MM.

DIM	MILLIMETERS		INCHES		DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX		MIN	MAX	MIN	MAX
A	4.00	BSC	0.157	BSC	V	1.95	2.25	0.076	0.088
B	4.00	BSC	0.157	BSC	W	0.98	1.13	0.039	0.044
C	---	1.00	---	0.039	Z	1.95	2.25	0.076	0.088
D	0.17	0.29	0.007	0.011	AA	---	0.80	---	0.031
E	3.75	BSC	0.148	BSC	AB	0.20	REF	0.008	REF
F	3.75	BSC	0.148	BSC	AD	0.98	1.13	0.039	0.044
G	0.50	BSC	0.020	BSC	AE	0.13	0.23	0.005	0.009
H	2.00	BSC	0.079	BSC	AF	0.24	0.60	0.009	0.024
K	0.00	0.05	0.000	0.002	AG	0.30	0.65	0.012	0.026
L	0.50	0.75	0.020	0.030					
M	---	12°	---	12°					
N	2.00	BSC	0.079	BSC					
P	1.88	BSC	0.074	BSC					
Q	0.50	DIA	0.020	DIA					
R	1.88	BSC	0.079	BSC					

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